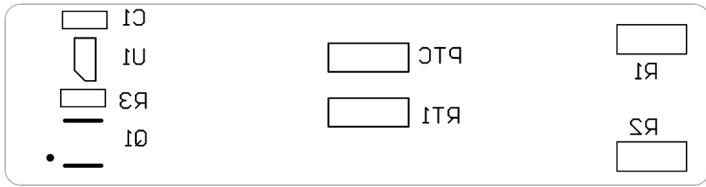
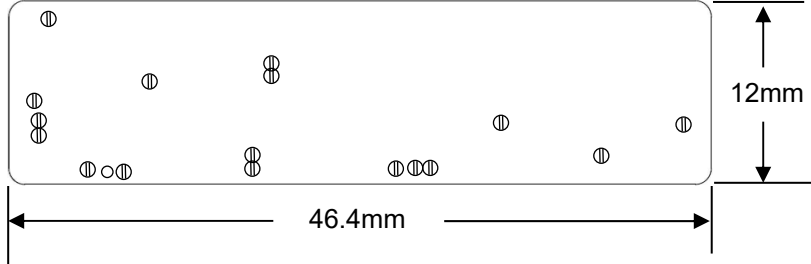


SILK PRINT FOR PARTS SIDE



THROUGH HOLE

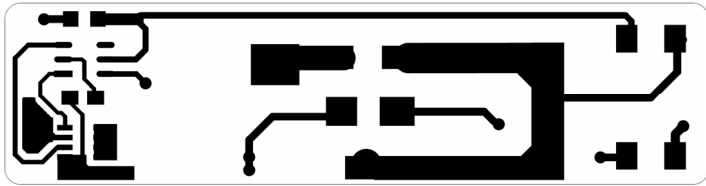


MARK	DIAGRAM	HOLE	MEMO
⊙	φ 0.5	TH	
○	φ 0.3	TH	

All drawings are view of parts side  
SCALE 2:1



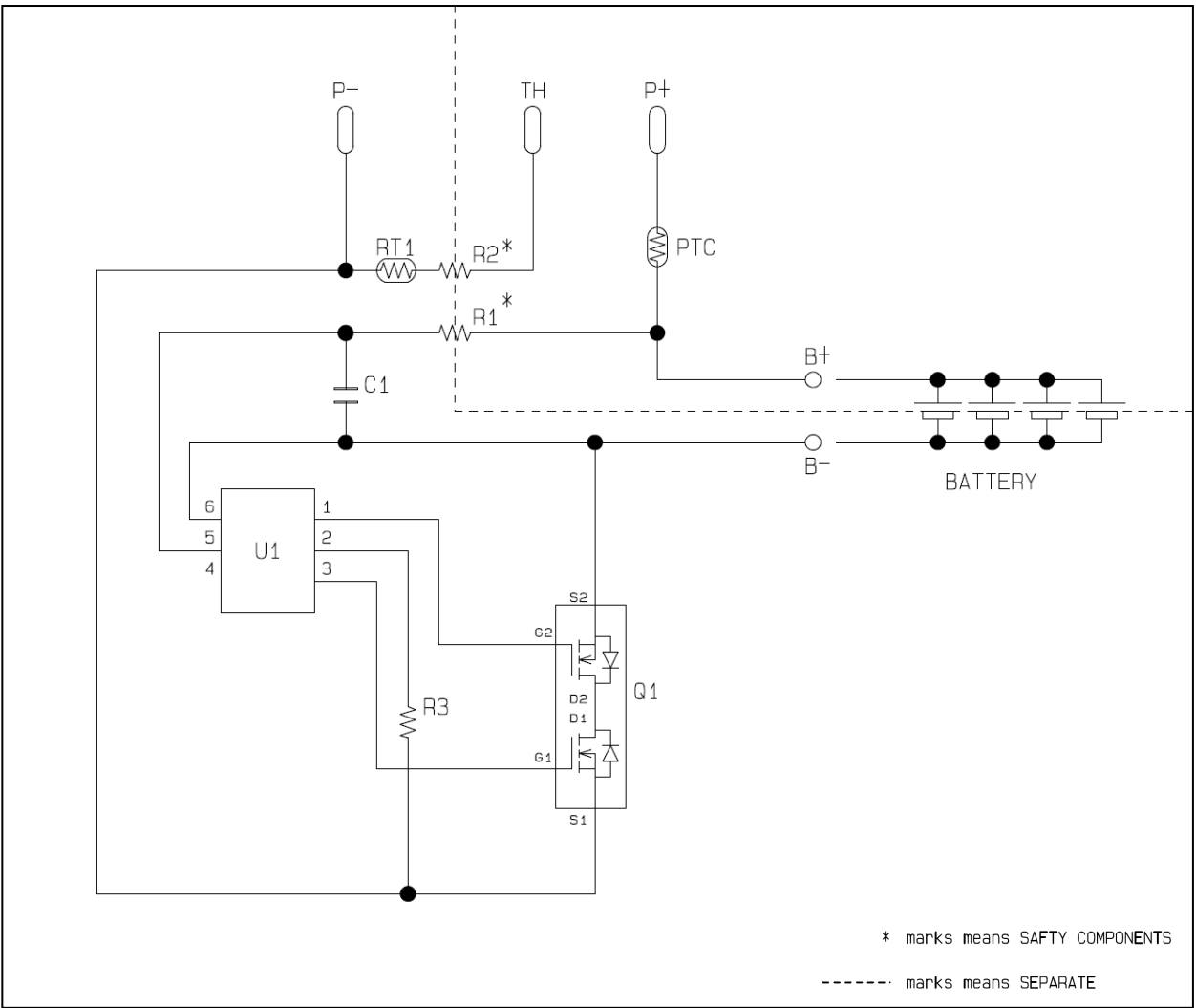
PARTS SIDE



SOLDERING SIDE

SPECIFICATION FOR PCB

- ・PCB No. : OE-2011773
- ・Material : Glass epoxy
- ・Thickness : 0.8mm-1.2mm
- ・Layer number : 2
- ・Thickness copper film : 35um
- ・Minimum conductor width : 0.3mm
- ・CTI : 100 above



SCHEMATIC

PARTS LIST

Mark of drawing	Kind of parts	Rating / Model of parts	Remarks
U1	Protect IC	S-8261ABRMD-G3RT2 [ABLIC]	
Q1	Nch MOSFET	HSBE2738 [HUASHUO]	
RT1	NTC Thermistor	Rt25 = 1k ohm – 470k ohm / 5%, B=3000K-5000K (3216)	
PTC	PTC Thermistor	JK-nSMD400L [Shenzhen Chengjuda Technology]	
R1	Chip metal film fixed resistor	470 ohm / 1%, 0.25W, 200V (3216)	*
R2	Chip metal film fixed resistor	470 ohm / 1%, 0.25W, 200V (3216)	*
R3	Chip fixed resistor or Chip jumper	10ohm - 10Mohm / 1%, 0.1W or 50m ohm max,1A (1608)	
C1	Chip multilayer Capacitor	0.11uFmax	

\* marked parts are Safety Components.

All components may be replaced with equivalent components or may not be mounted.

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME <b>PROTECT PCB</b>
改版回数 REV.	0	総頁数 PAGES	1	BP-E3
承 認 APPROVED	検 討 CHECKED	製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
山田和則	小野圭	木村司	2024.2.21	<b>E 3 - 6 9 9 1 - 6 5 2 2 - 7 0 - 0 1 K</b>